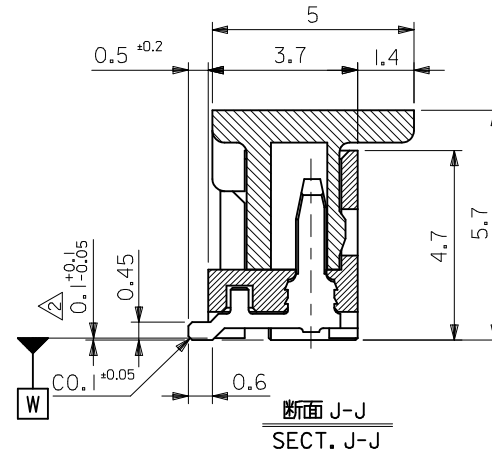


NOTES

1. 嵌合相手: 51021シリーズ MATE WITH : 51021 SERIES
2. 水平面上においての、ウエハー底面 **W** とソルダーテール及びフィッティングネイル底面とのズレ量を示す。
MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM **W**
3. 偶数極のみ適用。APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は 53398-***20 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-***20.



17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

MODEL NO. 53398-***29

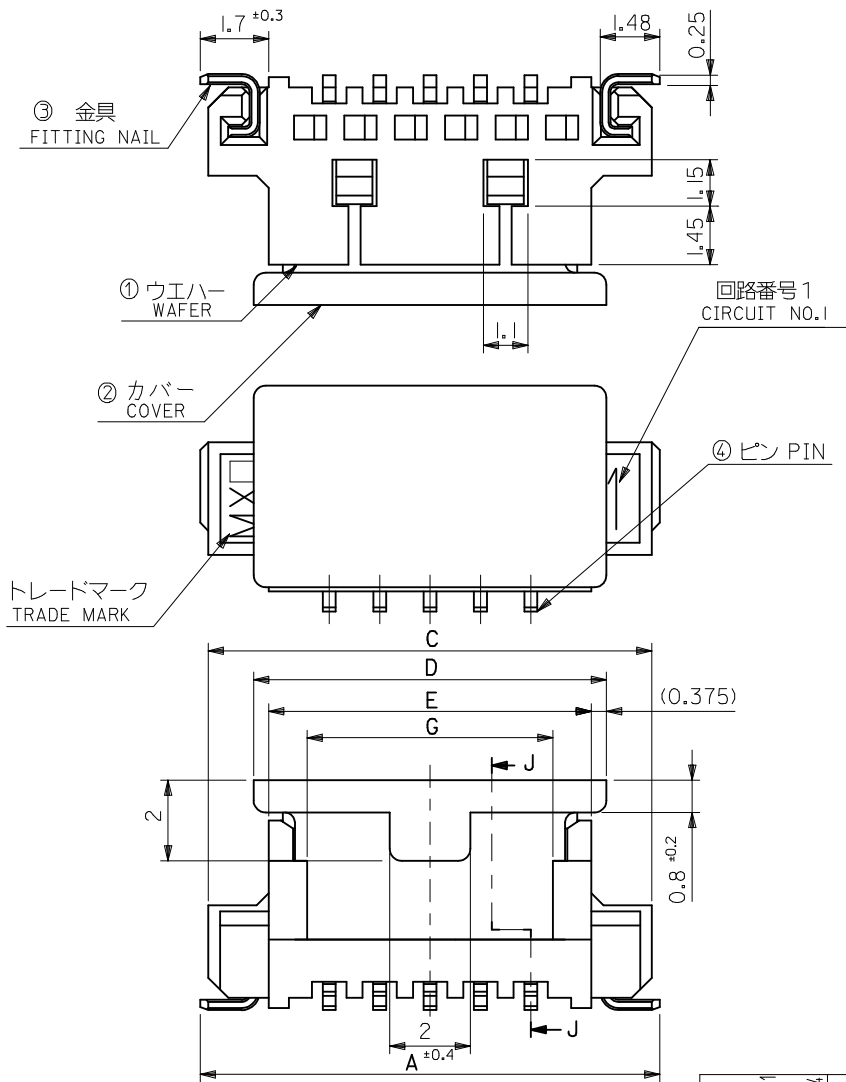
DISCRIPTION	MATERIAL
① WAFER	46NYLON (30% GLASS FILLED) UL94V-0
② COVER	
③ FITTING NAIL	リン青銅、ニッケル下地 無光沢鍍めつき PHOSPHOR BRONZE, PLATING : MATTE TIN 1.0 μm MIN. UNDERPLATE : NICKEL 1.0 μm MIN.
④ PIN	

REVISED
EC NO: J2017-0507
DRWN: S0BARA01 2017/03/31
CHKD:
APPR: KANEKO 2017/04/04

GENERAL TOLERANCES (UNLESS SPECIFIED)		
0.25 UNDER	UNDER	±0.03
0.25 OVER	0.5 UNDER	±0.05
0.5 OVER	1.0 UNDER	±0.1
1.0 OVER	30 UNDER	±0.2
10 OVER	30 UNDER	±0.25
30 OVER		±0.3
ANGULAR	±3 °	

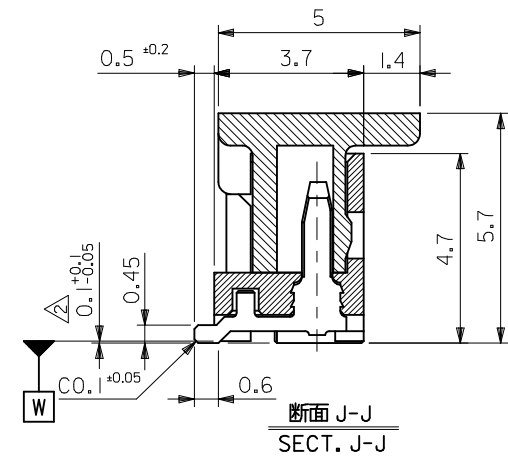
DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
Y. SAKIYAMA	2004/02/12
CHECKED BY	DATE
M. SASAO	2004/02/12
APPROVED BY	DATE
M. SASAO	2004/02/12
MATERIAL NO.	
SEE CHART	
SIZE	A3

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
8:1	METRIC	
TITLE		
PICOBLEAD 1.25 HEADER ASSY WITH COVER SMT ST TYPE		
molex		
DOCUMENT NO.	SHEET NO.	
SD-53398-034	1 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



NOTES

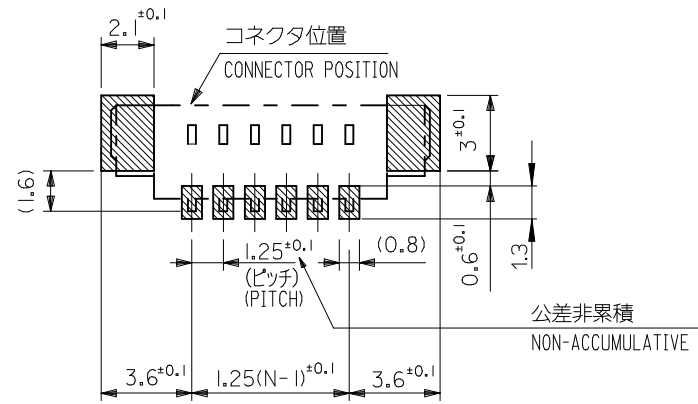
1. 嵌合相手: 51021シリーズ MATE WITH : 51021 SERIES
2. 水平面上において、ウエハー底面 **W** とソルダーテール及びフィッティングネイル底面とのズレ量を示す。
MISALIGNMENT OF SOLDER TAIL & FITTING NAIL FROM **W**
3. 偶数極のみ適用。APPLY EVEN CIRCUIT PRODUCTS.
4. 本製品は 53398-***20 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-***20.



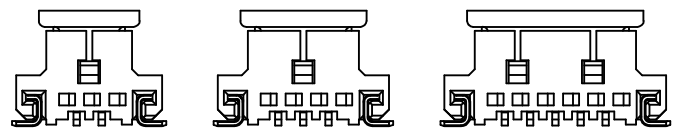
17.35	18.05	19.25	20	22.25	16.25	22.3	53398-1429	14
14.85	15.55	16.75	17.5	19.75	13.75	20.15	53398-1229	12
9.85	10.55	11.75	12.5	14.75	8.75	15.15	53398-0829	8
8.6	9.3	10.5	11.25	13.5	7.5	13.9	53398-0729	7
7.35	8.05	9.25	10	12.25	6.25	12.65	53398-0629	6
6.1	6.8	8	8.75	11	5	11.4	53398-0529	5
4.85	5.55	6.75	7.5	9.75	3.75	10.15	53398-0429	4
3.6	4.3	5.5	6.25	8.5	2.5	8.9	53398-0329	3
2.35	3.05	4.25	5	7.25	1.25	7.65	53398-0229	2
G	F	E	D	C	B	A	MATERIAL NO.	CIRCUITS

DISCRIPTION	MATERIAL
① WAFER	46NYLON (30% GLASS FILLED) UL94V-0
② COVER	
③ FITTING NAIL	リン青銅、ニッケル下地 無光沢鍍めつき PHOSPHOR BRONZE, PLATING : MATTE TIN 1.0 μm MIN. UNDERPLATE : NICKEL 1.0 μm MIN.
④ PIN	

REVISED EC NO: J2017-0507 DRWN:SOBARA01 2017/03/31 CHKD: APPR:TKANEKO 2017/04/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 8:1	DESIGN UNITS METRIC	MODEL NO. 53398-***29
	0.25 UNDER	UNDER	±0.03	DRAWN BY Y. SAKIYAMA	DATE 2004/02/12	TITLE PICOBLEAD 1.25 HEADER ASSY WITH COVER SMT ST TYPE	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY M. SASAO	DATE 2004/02/12	DOCUMENT NO. SD-53398-034	
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE 2004/02/12	SHEET NO. 1 OF 2	
1.0 OVER	30 UNDER	±0.2	MATERIAL NO.		SEE CHART		
10 OVER	30 UNDER	±0.25	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

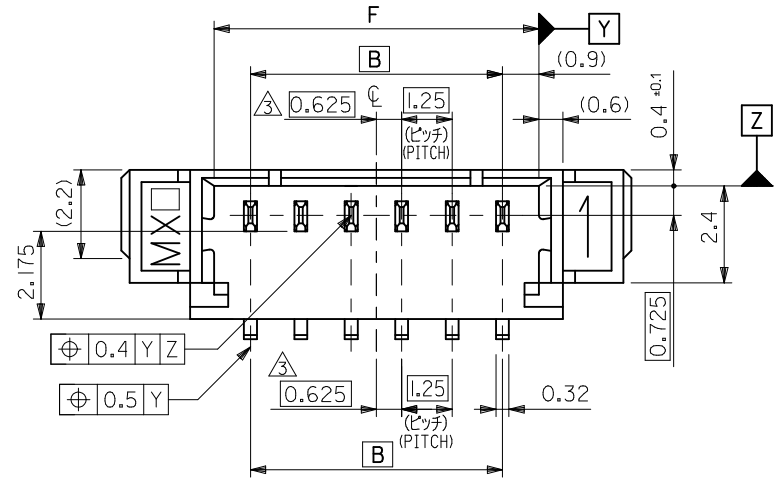


参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



2極 2 CKT.
3極 3 CKT.
4極以上 OVER 4 CKT.

△ ロック形状図
LOCK CONFIGURATION

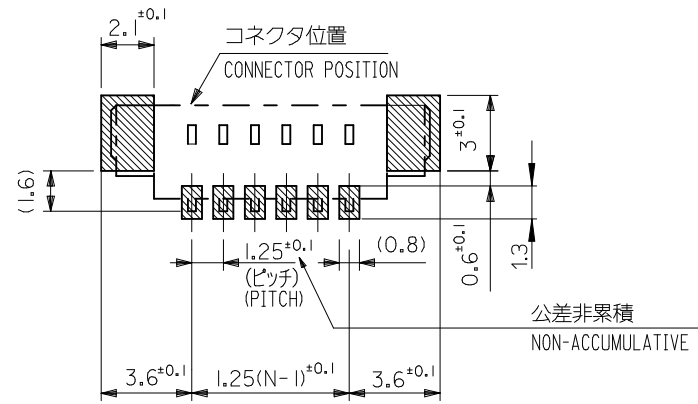


カバーなしの場合 (53398-***19)
IN CASE OF WITHOUT COVER

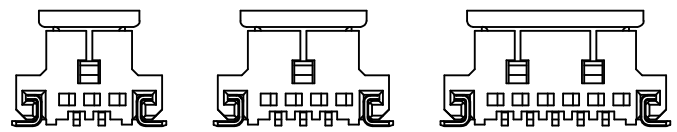
NOTES

- △ ロック窓は、2、3極は1ヶ所、4極以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.
- 6. ソルダータール及び金具の平坦度は0.1以下。
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

REVISED EC NO: J2017-0507 DRWN:SOBARA01 2017/03/31 CHKD: APPR:TKANEKO 2017/04/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 8:1	DESIGN UNITS METRIC	MODEL NO. 53398-***29
	0.25 UNDER	UNDER	±0.03	DRAWN BY Y. SAKIYAMA	DATE 2004/02/12	THIRD ANGLE PROJECTION	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY M. SASAO	DATE 2004/02/12	TITLE PICOBLADE 1.25 HEADER ASSY WITH COVER SMT ST TYPE	
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE 2004/02/12	DOCUMENT NO. SD-53398-034	
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.	SHEET NO. 2 OF 2		
30 OVER		±0.3	SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
ANGULAR ±3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		

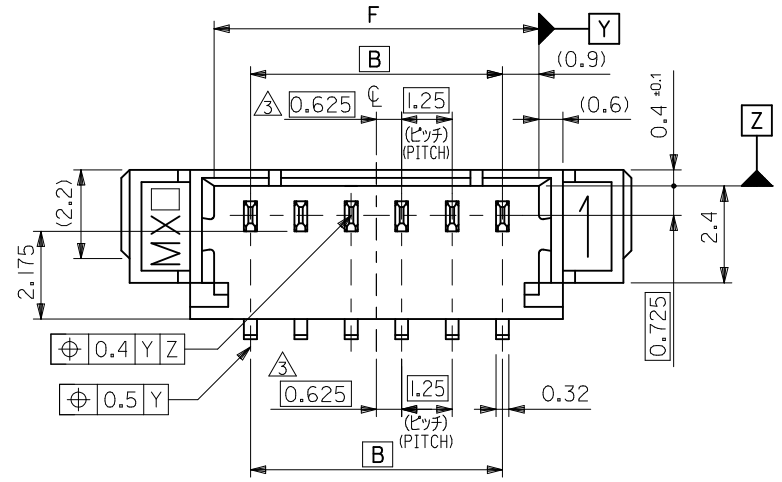


参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



2極 2 CKT.
3極 3 CKT.
4極以上 OVER 4 CKT.

ロック形状図
LOCK CONFIGURATION



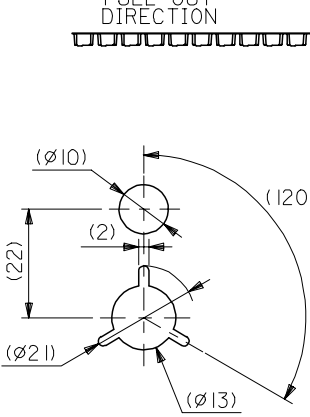
カバーなしの場合 (53398-***19)
IN CASE OF WITHOUT COVER

NOTES

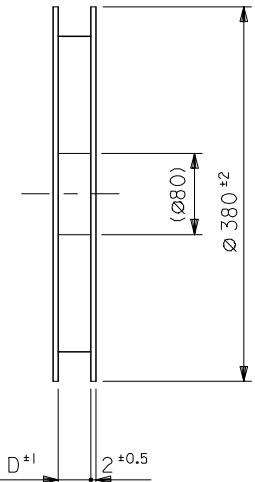
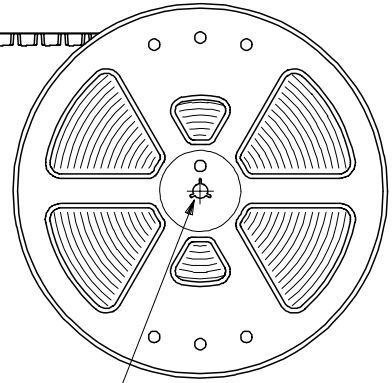
- △ ロック窓は、2、3極は1ヶ所、4極以上は2ヶ所とする。
LOCKING WINDOW : ONE PLACE FOR 2&3 CKTS.
TWO PLACES FOR MORE THAN 4 CKTS.
- 6. ソルダータール及び金具の平坦度は0.1以下。
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

REVISED EC NO: J2017-0507 DRWN:SOBARA01 2017/03/31 CHKD: APPR:TKANEKO 2017/04/04	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 8:1	DESIGN UNITS METRIC	MODEL NO. 53398-***29
	0.25 UNDER	UNDER	±0.03	DRAWN BY Y. SAKIYAMA	DATE 2004/02/12	TITLE PICOBLADE 1.25 HEADER ASSY WITH COVER SMT ST TYPE	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY M. SASAO	DATE 2004/02/12	THIRD ANGLE PROJECTION	
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE 2004/02/12	DOCUMENT NO. SD-53398-034	
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.	SHEET NO. 2 OF 2		
30 OVER		±0.3	SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		

引き出し方向
PULL OUT DIRECTION

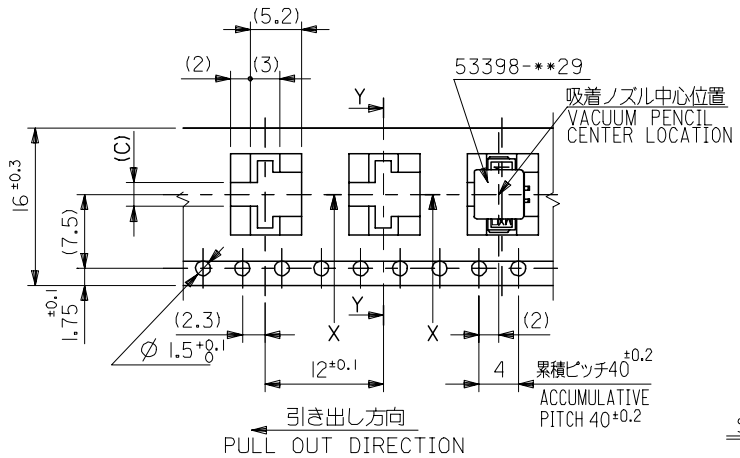
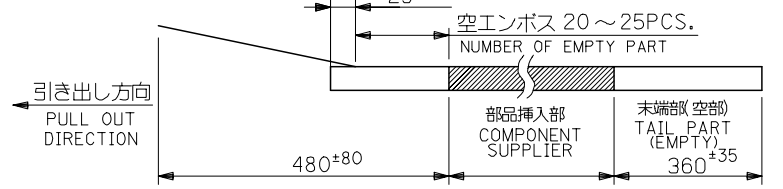


DETAIL "F"

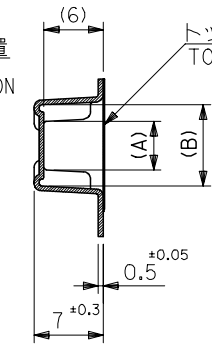


NOTES

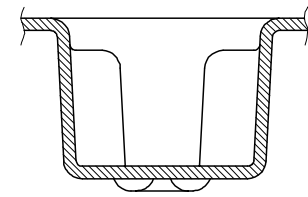
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH
トップテープ未接着部
TOP TAPE NON-BONDED PART
25±10
空インボス 20~25PCS.
NUMBER OF EMPTY PART
部品挿入部
COMPONENT SUPPLIER
末端部(空部)
TAIL PART (EMPTY)
360±35
480±80
引き出し方向
PULL OUT DIRECTION
- トップテープの剥離強度: 0.6±0.35N(60±35gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.6±0.35N(60±35gf)
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)
<剥離速度: 300mm/min(参考)>
PEELING SPEED: 300mm/min. (REFERENCE)
剥離方向
PEEL OFF DIRECTION
10°
引き出し方向
PULL OUT DIRECTION
- 53398-***29の詳細寸法については図面 SD-53398-034 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53398-034.
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は 53398-***80 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53398-***80.



16幅テープ
(TAPE WIDTH: 16)



SECT: Y-Y



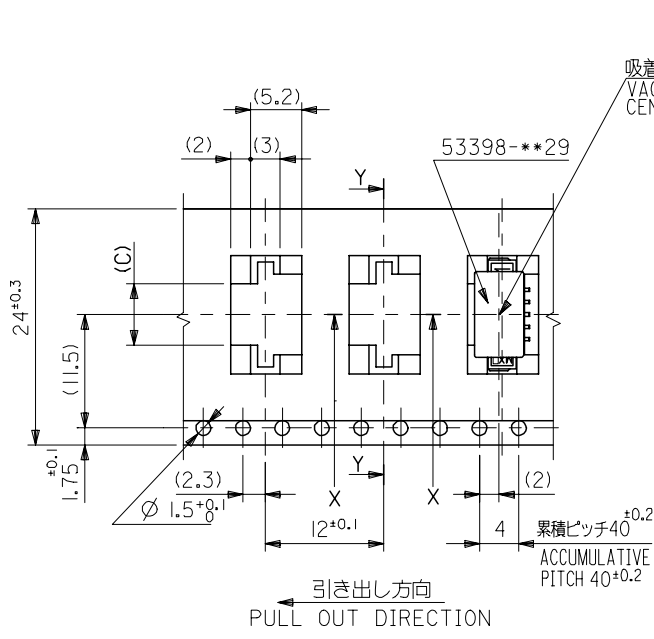
SECT: X-X

32	33.4	14.95	20.75	17.05	53398-1267	12
24	25.4	9.95	15.75	12.05	53398-0867	8
		8.7	14.5	10.8	53398-0767	7
		7.45	13.25	9.55	53398-0667	6
		6.2	12	8.3	53398-0567	5
		4.95	10.75	7.05	53398-0467	4
16	17.4	2.45	8.25	4.55	53398-0267	2
キャリアテープ幅 CARRIER TAPE WIDTH	D	(C)	(B)	(A)	MATERIAL NO.	CIRCUITS

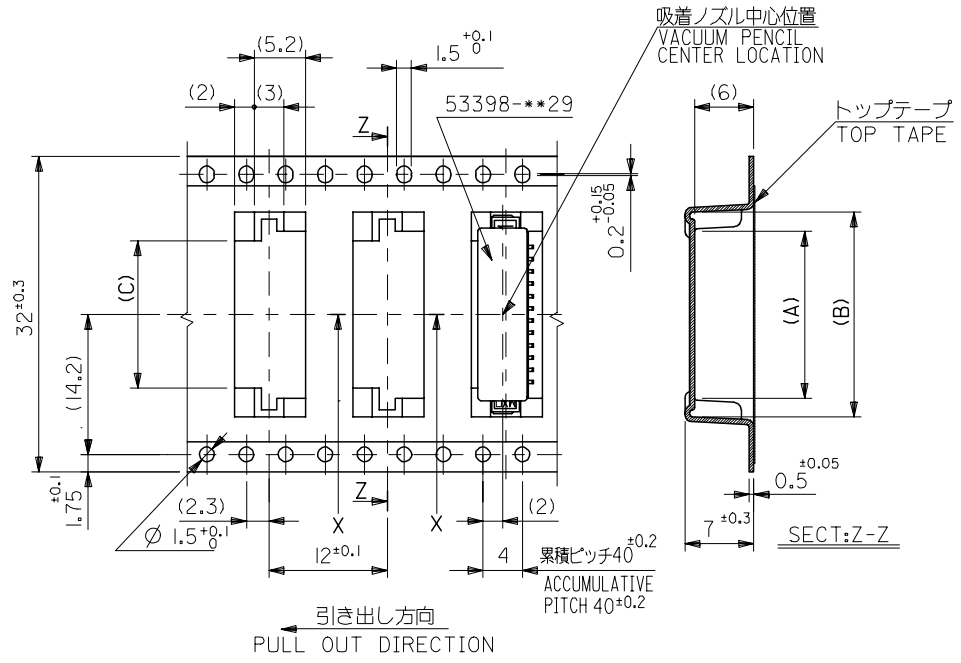
REVISED EC NO: DRAWN BY CHKD BY APPD BY REV	DESCRIPTION 2004/07/28 MURIGUCHI 2004/07/28 ASAKAWA 2004/07/30 SICHIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY J. SASAMO	DATE 2004/7/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/7/22				
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2004/7/22	MOLEX INCORPORATED			
		ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53398-035		1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

10 9 8 7 6 5 4 3 2 1

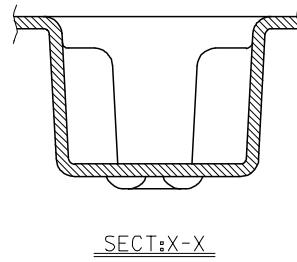
F
E
D
C
B
A



24幅テープ
(TAPE WIDTH:24)



32幅テープ
(TAPE WIDTH:32)



SECT:X-X

REVISED EC NO: 2004/07/28 DRAWN: M. I. GUCH CHKD: K. ASAKAW APPR: S. ICHIKAW 2004/07/28 2004/07/28 2004/07/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY J. SASAMO	DATE 2004/7/22	TITLE EMBSTP PKG FOR 1.25 W/B CONN. WAFER ASSY -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/7/22	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2004/7/22	DOCUMENT NO. SD-53398-035	SHEET NO. 2 OF 2
	ANGULAR	±3 °	MATERIAL NO. SEE CHART			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

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